

LINEAR TECHNOLOGY MATERIALS DECLARATION

1t1004cz-1.2#trpbf

(Engineering Calculation)

TO-92

(printed on: 2020-07-11 19:37:25)

TOTAL MASS (g) : 0.204729

| COMPONENT MATERIAL | VENDOR/ INDUSTRY NAMES | CONSTITUENT NAME | CAS NUMBER | CONSTITUENT MASS (g) | CONSTITUENT (PPM) OF MATERIAL | CONSTITUENT (PPM) OF TOTAL PKG. | | |
|--------------------------------|----------------------------------|--------------------------------|------------|----------------------|-------------------------------|---------------------------------|----------------|----------------------|
| Active Device | Linear Technology | Silicon (Si) | 7440-21-3 | 0.001642 | 1000000 | 8020.35058594 | | |
| Die Coat | Dow Corning | Silicone | 69430-27-9 | 0.000000 | 0 | 0 | | |
| Lead Frame | Cu | Copper (Cu) | 7440-50-8 | 0.088433 | 975000 | 431951.0625 | | |
| | | Iron (Fe) | 7439-89-6 | 0.002177 | 24000 | 10633.5585938 | | |
| | | Phosphorus (P) | 7723-14-0 | 0.000027 | 300 | 131.881530762 | | |
| | | Zinc (Zn) | 7440-66-6 | 0.000063 | 700 | 307.723571777 | | |
| | | Nickel (Ni) | 7440-02-0 | 0.000000 | 0 | 0 | | |
| | | Silicon (Si) | 7440-21-3 | 0.000000 | 0 | 0 | | |
| | | Magnesium (Mg) | 7439-95-4 | 0.000000 | 0 | 0 | | |
| | | Tin (Sn) | 7440-31-5 | 0.000000 | 0 | 0 | | |
| Lead Frame Total: | | | | 0.090700 | 1000000 | 443024.25 | | |
| Plating | PMI | Exter. Plating Pb | 7439-92-1 | 0.000000 | 0 | 0 | | |
| | | Exter. Plating Sn | 7440-31-5 | 0.005680 | 1000000 | 27744.9414062 | | |
| | | External Plating Total: | | | | 0.005680 | 1000000 | 27744.9414062 |
| | | Inter. Plating Ni | 7440-02-0 | 0.000000 | 0 | 0 | | |
| | | Inter. Plating Ag | 7440-22-4 | 0.000320 | 1000000 | 1563.0402832 | | |
| Internal Plating Total: | | | | 0.000320 | 1000000 | 1563.0402832 | | |
| Die Attach | ELECTRICALLY CONDUCTIVE ADHESIVE | Silver (Ag) | 7440-22-4 | 0.000603 | 750000 | 2945.35424805 | | |
| | | Tin (Sn) | 7440-31-5 | 0.000000 | 0 | 0 | | |
| | | Lead (Pb) | 7439-92-1 | 0.000000 | 0 | 0 | | |
| | | Silica (SiO2) | 60676-86-0 | 0.000000 | 0 | 0 | | |
| | | Indium (In) | 7440-74-6 | 0.000000 | 0 | 0 | | |
| | | Metal Oxide | | 0.000000 | 0 | 0 | | |
| | | Antimony (Sb) | 7440-36-0 | 0.000000 | 0 | 0 | | |
| | | Resin (EP) | | 0.000201 | 250000 | 981.784790039 | | |
| Die Attach Total: | | | | 0.000804 | 1000000 | 3927.13916016 | | |
| Encapsulation | MULTI-AROMATIC RESIN Br/Sb FREE | Resin (EP) | | 0.014243 | 135000 | 69569.953125 | | |
| | | Bromine (Br) | 40039-93-8 | 0.000000 | 0 | 0 | | |
| | | Silica (SiO2) | 60676-86-0 | 0.090730 | 860000 | 443170.75 | | |
| | | Antimony Trioxide (Sb2O3) | 1309-64-4 | 0.000000 | 0 | 0 | | |
| | | Metal Hydroxide | | 0.000000 | 0 | 0 | | |
| | | Carbon Black (C) | 1333-86-4 | 0.000528 | 5000 | 2579.01660156 | | |
| | | Encapsulation Total: | | | | 0.105501 | 1000000 | 515319.75 |
| Bond Wire Estimated | AFW/TANAKA/ Kn | Gold (Au) | 7440-57-5 | 0.000082 | 1000000 | 400.529083252 | | |
| | | | | | TOTAL MASS (g) : | 0.204729 | | |